



High-end Power Semiconductor Manufacturer

ZP7100 - WELDING DIODE**200-400 V_{DRM}****WELDING DIODE****Features:**

- . All diffused structure
- . High current density
- . Very low forward voltage drop
- . Ceramic housing hermetic package
- . Ultra-low thermal resistance

**ELECTRICAL CHARACTERISTICS AND RATINGS****Reverse Blocking**

| Device Type | V _{RRM} (1) | V _{RSM} (1) |
|-------------|----------------------|----------------------|
| ZP7100 -02 | 200 | 300 |
| ZP7100 -04 | 400 | 450 |

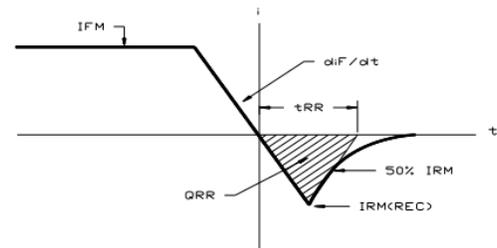
V_{RRM} = Repetitive peak reverse voltageV_{RSM} = Non repetitive peak reverse voltage (2)

| Repetitive peak reverse leakage current | I _{RRM} | 15 mA 50 mA (3) |
|---|------------------|--------------------|
| | | |

Notes:

All ratings are specified for T_j=25 °C, unless otherwise stated(1) Sine half wave, f=50Hz, T_j = -40 to +170°C.(2) Sine half wave, Pulse width 10 msec. T_j = -40 to +170°C.(3) Maximum value for T_j = 170 °C.

(4) See parameter definition below :



REVERSE RECOVERY CHARACTERISTIC

Conducting - on state

| Parameter | Symbol | Min. | Max. | Typ. | Units | Conditions |
|---|----------------------|------|-------|------|-------------------|--|
| Average forward current | I _{F(AV)} | | 7100 | | A | Sinewave 180°, T _c =85°C |
| RMS forward current | I _{FRMS} | | 11200 | | A | |
| Peak one cycle surge (non repetitive) current | I _{FSM} | | 55000 | | A | Pulse width 10 msec, sinusoidal wave-shape, 180° conduction, T _j = 170 °C |
| I square t | I ² t | | 15100 | | KA ² s | Pulse width 10 msec, sinusoidal wave-shape, T _j = 170 °C |
| Peak forward voltage | V _{FM} | | 1.05 | | V | I _{FM} = 5000A; 25°C |
| Threshold voltage | V _{TO} | | 0.74 | | V | T _j = 170 °C |
| Slope resistance | r _T | | 0.026 | | mΩ | T _j = 170 °C |
| Reverse Recovery Current (4) | I _{RM(REC)} | | | | A | I _{FM} = 1000 A; dI/dt = 10 A/μs; T _j max |
| Reverse Recovery Charge (4) | Q _{rr} | | | | μC | I _{FM} = 1000 A; dI/dt = 10 A/μs; T _j max |
| Reverse Recovery Time (4) | t _{rr} | | | | μs | I _{FM} = 1000 A; dI/dt = 10 A/μs; T _j max |

* For guaranteed maximum values, contact factory

| Parameter | Symbol | Min. | Max. | Typ. | Units | Conditions |
|---------------------------------------|-------------------|------|------|------|-------|---------------------|
| Operating temperature | T_j | -40 | +170 | | °C | |
| Storage temperature | T_{stg} | -40 | +170 | | °C | |
| Thermal resistance - junction to case | $R_{\Theta(j-c)}$ | | 0.01 | | °C/W | Double sided cooled |
| Thermal resistance - junction to case | $R_{\Theta(j-c)}$ | | 0.02 | | °C/W | Single sided cooled |
| Creepage distance | D_s | | 4 | | mm | |
| Air breakdown distance | D_a | | 4 | | mm | |
| Mounting force | F | | | 24 | kN | |
| Weight | W | | | 140 | g | |

* Mounting surfaces smooth, flat and greaseless

CASE OUTLINE AND DIMENSIONS

